DATE: 7/25/16

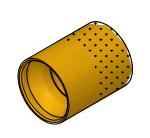
CATALOG NUMBER	"A" INTERFACE	
B012-L93-04-T	FULL DETENT	
B012-L94-04-T	LIMITED DETENT	
B012-L95-04-T	SMOOTH BORE	

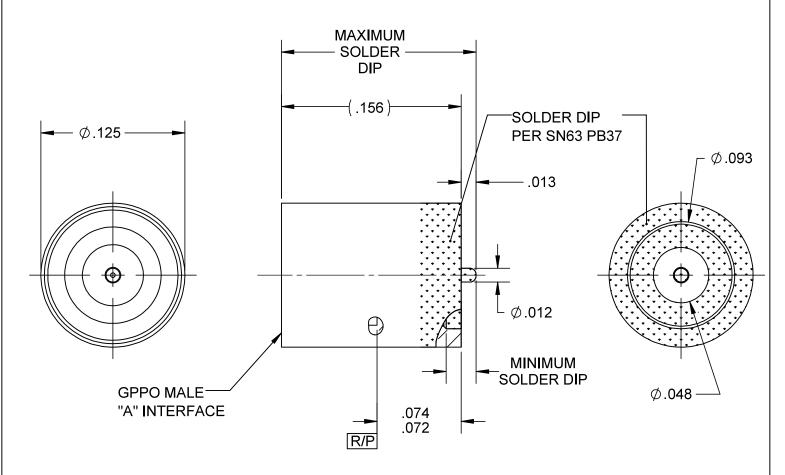
MATERIAL AND FINISH

HOUSING, BUSHING BeCu; GOLD PLATE 75 MICROINCHES TYPICAL

AND CENTER CONTACT: OVER COPPER FLASH

DIELECTRICS: POLYAMIDE-IMIDE





NOTES:



NON-MAGNETIC PLATING. THIS CONNECTOR IS NOT TO BE USED IN STANDARD APPLICATIONS.

ALL DIMENSIONS APPLY BEFORE SOLDER DIP. 2.

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APPROX. WEIGHT:	0.1472	grams			
TOLERANCE:					
.XX ±.010 .XXX ±.005 ANGULAR ±5°					

SIGNATURES		INIT	DATE:
DRAWN:	TEF		7/25/16
CHECKED:	DMG		
APPROVED:	TEF		

PLANT OF ORIGIN

GPPO MALE PCB, HIGH **IMPEDENCE SOLDER TERMINATION (TAB DETENT)** **CAGE CODE:** SCALE: 12:1 82316

REVISION:

CORNING PHOENIX PLANT: (623)245-1050 CUSTOMER SERVICE: (800) 651-8869

SOURCE ASSY. SK-4644 OL-B012-L9X-04-T DWG. NO .: PROC.